ABSTRACT

FIBER ARRAY WITH SIDE POLISHING FOR IMPROVED FIBER POSITION WITH WAFER SUBSTRATE OR CHIP

A fiber array for edge coupling of at least one optical fiber with at least one wafer substrate is provided. The fiber array includes an optical fiber core; a cladding covering the optical fiber core; and a polished and tapered lid at the bottom of the cladding.

FIG. 4 accompanies the abstract.